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March 2014



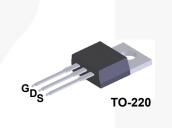
FQP12N60C N-Channel QFET[®] MOSFET 600 V, 12 A, 650 mΩ

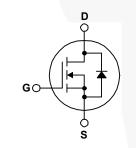
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.

Features

- + 12 A, 600 V, $R_{DS(on)}$ = 650 m Ω (Max.) @ V_{GS} = 10 V, I_{D} = 6 A
- Low Gate Charge (Typ. 48 nC)
- Low Crss (Typ. 21 pF)
- 100% Avalanche Tested





Absolute Maximum Ratings T_c = 25°C unless otherwise noted.

Symbol	Parameter Drain-Source Voltage		FQP12N60C	Unit V	
V _{DSS}			600		
ID	Drain Current - Continuous - Continuous	$(T_{C} = 25^{\circ}C)$ $(T_{C} = 100^{\circ}C)$	12 7.4	A A	
I _{DM}	Drain Current - Pulsed	(Note 1)	48	A	
V _{GSS}	Gate-Source voltage		± 30		
E _{AS}	Single Pulsed Avalanche Energy (Note 2) 870		870	mJ	
I _{AR}	Avalanche Current	(Note 1)	12	A	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	22.5		
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V/ns	
P _D	Power Dissipation (T _C = 25°C) - Derate above 25°C		225 1.78		
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
Τ _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FQP12N60C	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.56	°C/W	
R_{\thetaJA}	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

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Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP12N60C	FQP12N60C	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics T_c = 25°C unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Off Charac	teristics				L	I
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA, T _J = 25°C	600			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C		0.5		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}$			1 10	μΑ μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30 V, V_{DS} = 0 V			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6 A		0.53	0.65	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 6 A	-	13		S
Dynamic C	haracteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 V, V_{GS} = 0 V,$		1760	2290	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		182	235	pF
C _{rss}	Reverse Transfer Capacitance			21	28	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	V_{DD} = 300 V, I _D = 12 A R _G = 25 Ω (Note 4)		30	70	ns
t _r	Turn-On Rise Time			85	180	ns
t _{d(off)}	Turn-Off Delay Time			140	280	ns
t _f	Turn-Off Fall Time			90	190	ns
Qg	Total Gate Charge	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 12 \text{ A}$ $V_{GS} = 10 \text{ V}$		48	63	nC
Q _{gs}	Gate-Source Charge			8.5		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		21		nC
Drain-Sour	ce Diode Characteristics and Maximur	n Ratings	1			
I _S	Maximum Continuous Drain-Source Diode Forward Current				12	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				48	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 12 A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 12 A		420		ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs		4.9		μC

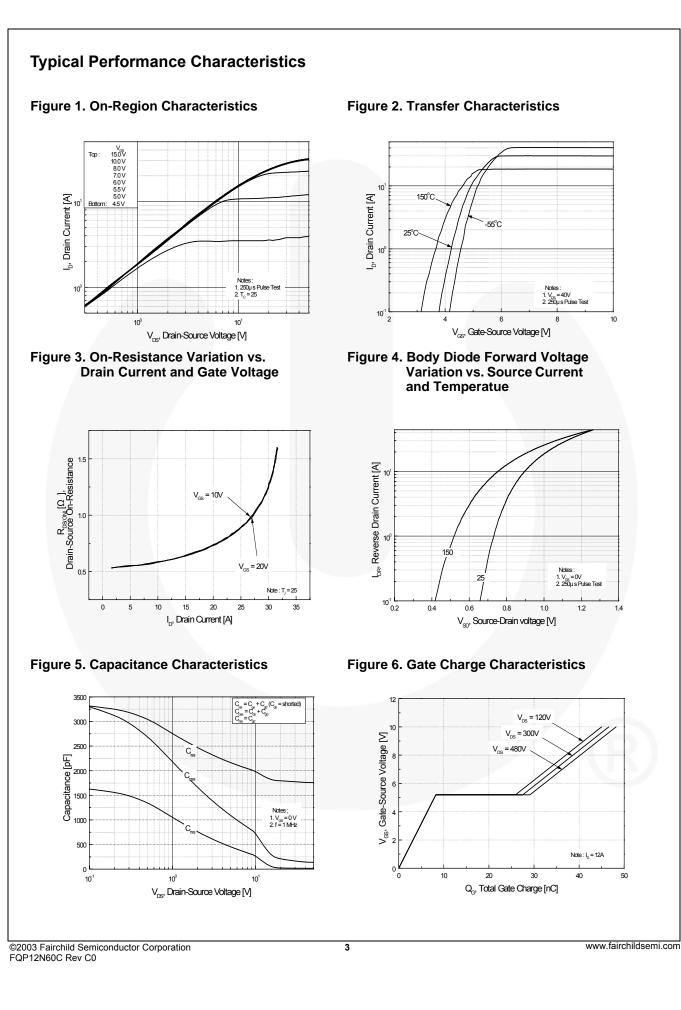
NOTES:

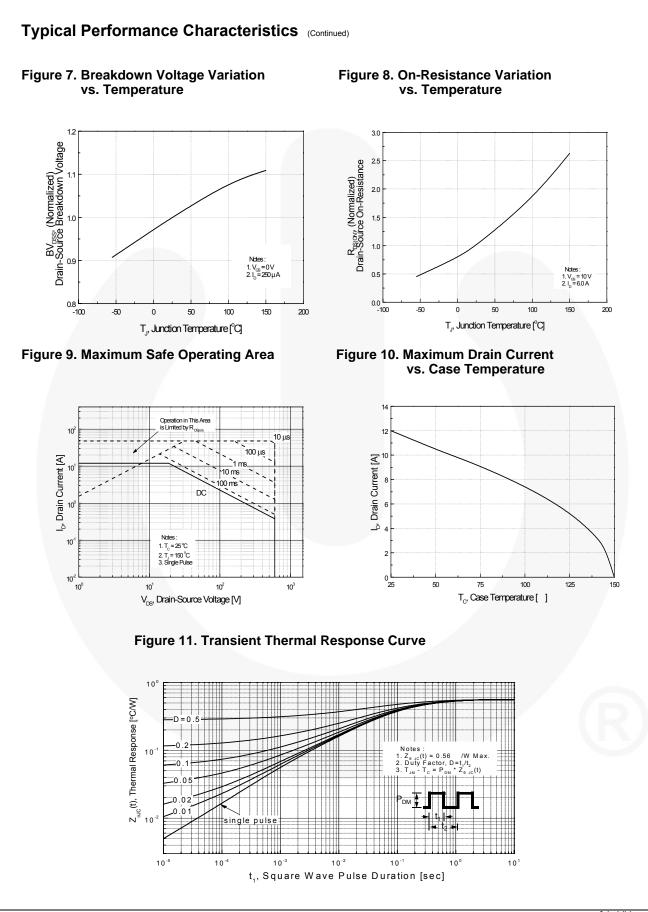
1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. L = 11 mH, I_{AS} = 12 A, V_{DD} = 50 V, R_G = 25 $\Omega,$ starting T_J = 25°C.

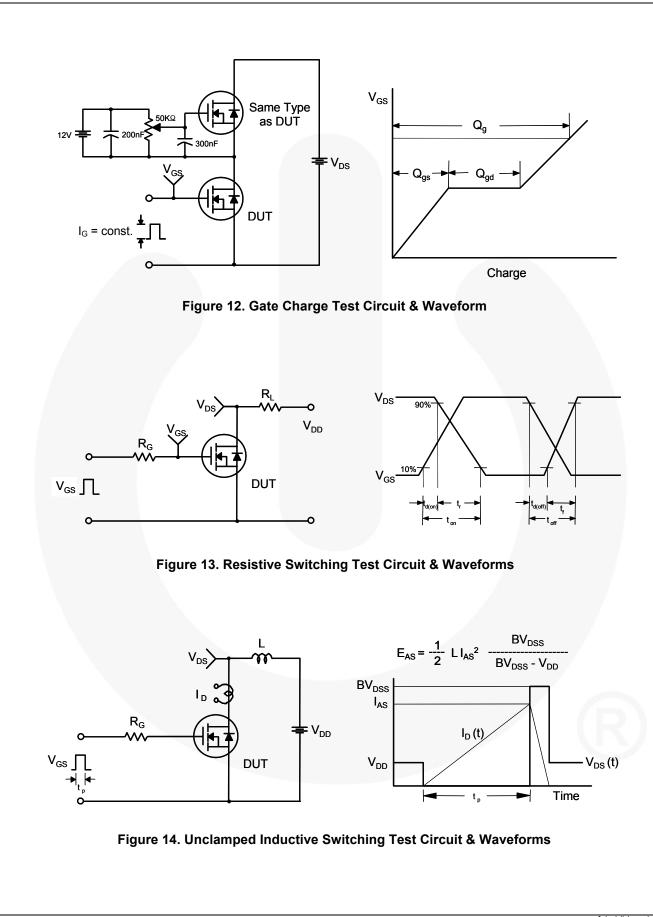
 $3.I_{SD} \leq$ 12 A, di/dt \leq 200 A/µs, $V_{DD} \leq BV_{DSS},$ starting T_J = 25°C.

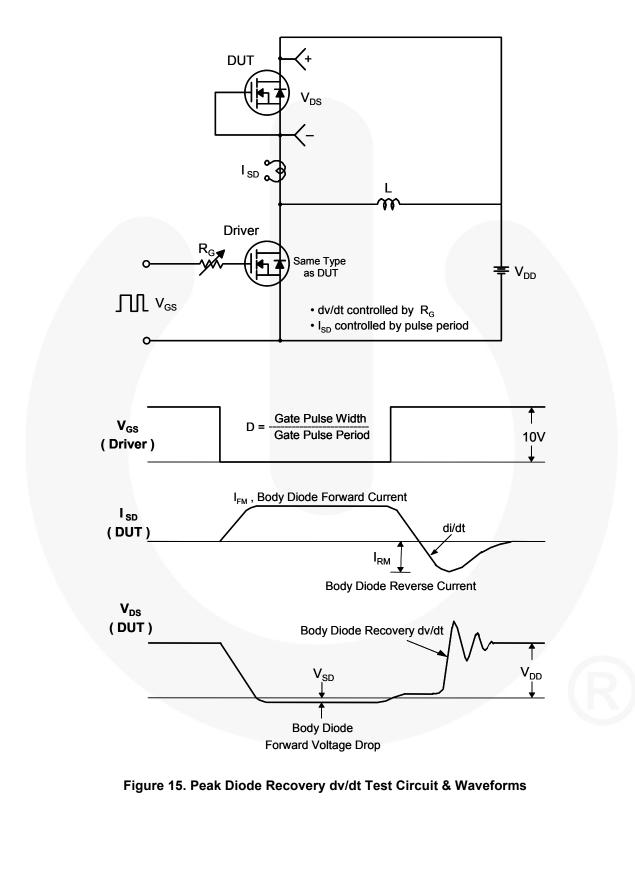
4. Essentially independent of operating temperature typical characteristics.



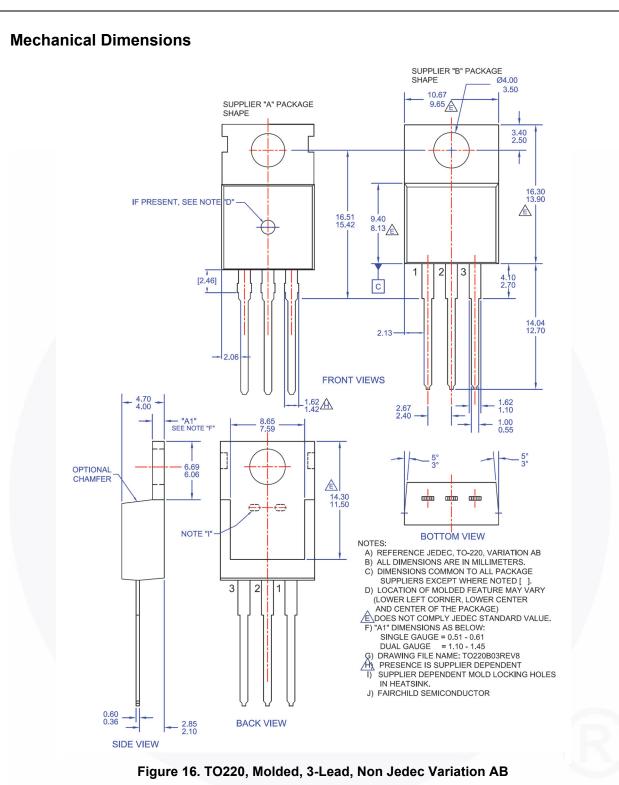


FQP12N60C — N-Channel QFET® MOSFET





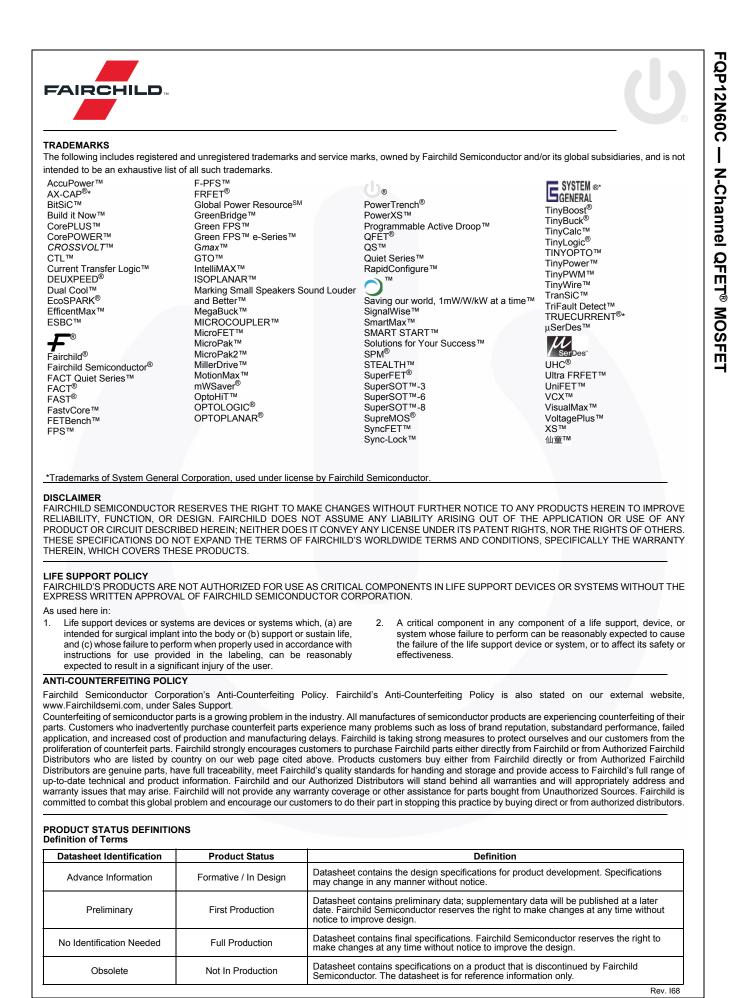




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